

Product Change Notification - RMES-28HUEN707

Date: 23 Nov 2017
Product Category: Linear Regulators
Notification subject: CCB 2883 Final Notice: Qualification of JCET as an additional assembly site for selected products of 135K DLM wafer technology available in 3L SOT-23A package using CuPdAu bond wire.
Notification text: **PCN Status:**
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of JCET as an additional assembly site for selected products of 135K DLM wafer technology available in 3L SOT-23A package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at HANA and LPI using gold (Au) bond wire and G600 molding compound material.

Post Change:

Assembled at HANA and LPI using gold (Au) bond wire and G600 molding compound material.

Assembled at JCET using palladium coated copper with gold flash (CuPdAu) bond wire and EMG 600-2 molding compound material.

Pre and Post Change Summary:

	Pre Change		Post Change		
	Hana Semiconductor CO., LTD. (HANA)	Lingsen Precision Industries, LTD.(LPI)	Hana Semiconductor CO., LTD. (HANA)	Lingsen Precision Industries, LTD.(LPI)	Jiangsu Changjiang Electronics Technology Co.,Ltd (JCET)
Assembly Site	Hana Semiconductor CO., LTD. (HANA)	Lingsen Precision Industries, LTD.(LPI)	Hana Semiconductor CO., LTD. (HANA)	Lingsen Precision Industries, LTD.(LPI)	Jiangsu Changjiang Electronics Technology Co.,Ltd (JCET)
Wire material	Au wire	Au wire	Au wire	Au wire	CuPdAu wire
Die attach material	8006NS	84-3J	8006NS	84-3J	8006NS
Molding compound material	G600	G600	G600	G600	EMG 600-2
Lead frame material	A194	EFTEC64T	A194	EFTEC64T	A194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at JCET assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
December 23, 2017(datecode: 1751)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2017					-->	November 2017					December 2017				
	09	10	11	12	13		44	45	46	47	48	49	50	51	52	
Initial PCN Issue Date					X											
Qual Report Availability									X							
Final PCN Issue Date									X							
Estimated Implementation Date													X			

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:
April 04, 2017: Issued initial notification.
April 05, 2017: Corrected typographical error on the revision history from March to April.
November 23, 2017: Issued final notification. Attached the Qualification Report. Removed CCB 2882. Revised the affected parts list. Provided estimated first ship date on December 23, 2017.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):
[PCN_RMES-28HUEN707_Affected_CPN.pdf](#)
[PCN_RMES-28HUEN707_Qual Report.pdf](#)
[PCN_RMES-28HUEN707_Affected_CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_RMES-28HUEN707
CATALOG_PART_NBR
MCP1702T-1202E/CB
MCP1702T-1502E/CB
MCP1702T-1802E/CB
MCP1702T-2102E/CB
MCP1702T-2202E/CB
MCP1702T-2302E/CB
MCP1702T-2502E/CB
MCP1702T-2702E/CB
MCP1702T-2802E/CB
MCP1702T-3002E/CB
MCP1702T-3302E/CB
MCP1702T-3602E/CB
MCP1702T-4002E/CB
MCP1702T-4101E/CB
MCP1702T-4502E/CB
MCP1702T-4702E/CB
MCP1702T-5002E/CB
MCP1702T-5102E/CB
MCP1703AT-1202E/CB
MCP1703AT-1502E/CB
MCP1703AT-1802E/CB
MCP1703AT-2052E/CB
MCP1703AT-2502E/CB
MCP1703AT-2802E/CB
MCP1703AT-3002E/CB
MCP1703AT-3152E/CB
MCP1703AT-3302E/CB
MCP1703AT-3302E/CBAAC
MCP1703AT-3502E/CB
MCP1703AT-4002E/CB
MCP1703AT-5001E/CB
MCP1703AT-5001E/CBAAA
MCP1703AT-5002E/CB
MCP1703T-1202E/CB
MCP1703T-1502E/CB
MCP1703T-1802E/CB
MCP1703T-2402E/CB
MCP1703T-2502E/CB
MCP1703T-2802E/CB
MCP1703T-3002E/CB
MCP1703T-3301E/CB
MCP1703T-3302E/CB
MCP1703T-3502E/CB

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Affected Catalog Part Numbers (CPN)

PCN_RMES-28HUEN707
CATALOG_PART_NBR
MCP1703T-3602E/CB
MCP1703T-4002E/CB
MCP1703T-4502E/CB
MCP1703T-5001E/CB
MCP1703T-5002E/CB
MCP1703T-5002E/CBHAZ